

JAPANESE PATENT OFFICE
PATENT JOURNAL
KOKAI PATENT APPLICATION NO. HEI 2[1990]-207562

Int. Cl.⁵: H 01 L 25/04
25/00
25/065
25/07
25/18
H 01 L 25/04
25/08

Sequence Nos. for Office Use: 7638-5F
7638-5F
7638-5F

Application No.: Hei 1[1989]-27420

Application Date: February 8, 1989

Publication Date: August 17, 1990

No. of Claims: 1 (Total of 2 pages)

Examination Request: Not requested

MODULE PACKAGING STRUCTURE

Inventors: Masaaki Kamemura
Kanagawa Plant,
Hitachi, Ltd.,
1 Horiyamashita,
Hadano-shi, Kanagawa-ken

Bunichi Tanoue
Kanagawa Plant,
Hitachi, Ltd.,
1 Horiyamashita,
Hadano-shi, Kanagawa-ken

Applicant:

Hitachi, Ltd.,
4-6 Surugadai, Kanda,
Chiyoda-ku, Tokyo

Agents:

Katsuo Ogawa, patent
attorney, and 1 other

[There are no amendments to this patent.]

Claim

Module packaging structure characterized in that, in a module that connects logic elements, there are connection points on the sides, bottom, top, or entire surface of the module, with devices being constructed by stacking a number of said modules into a three-dimensional manner.

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